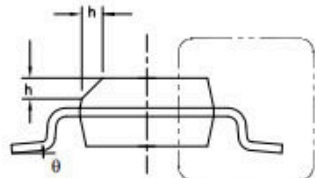
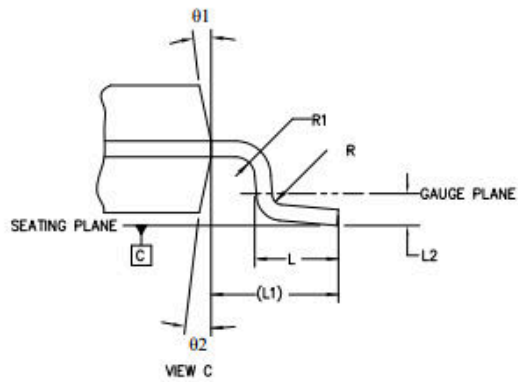


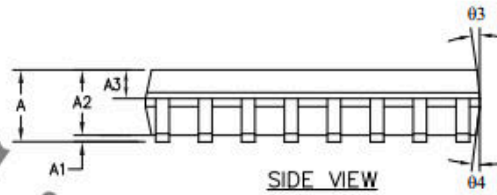
TOP VIEW



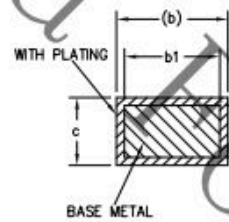
SEE VIEW C



VIEW C



SIDE VIEW



SYMBOL	MIN	NOM	MAX
A	1.45	---	1.8
A1	0.10	0.15	0.25
A2	1.35	1.45	1.55
A3	0.55	0.65	0.75
b	0.36	---	0.51
b1	0.35	0.40	0.45
c	0.18	---	0.25
c1	0.17	0.20	0.23
D	9.80	9.90	10.00
e	1.27BSC		
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
L	0.45	0.60	0.80
L1	1.04REF		
L2	0.25BSC		
R	0.07	---	---
R1	0.07	---	---
h	0.30	0.40	0.50
θ	0°	---	8°
θ1	6°	8°	10°
θ2	6°	8°	10°
θ3	5°	7°	9°
θ4	5°	7°	9°

NOTES: 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-137E2. DIMENSION D DOES NOT INCLUDE MOLD FLASH. 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH. 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.



上海季丰电子科技有限公司  
GIGA FORCE ELECTRONICS CO., Limited

制图	王磊	Title	Package Outline SOP16	
核准	何桂港	POD No	POD-SHJF-35	
日期	2022. 3. 31	DIMENSIONS IN:	mm	Rev: A